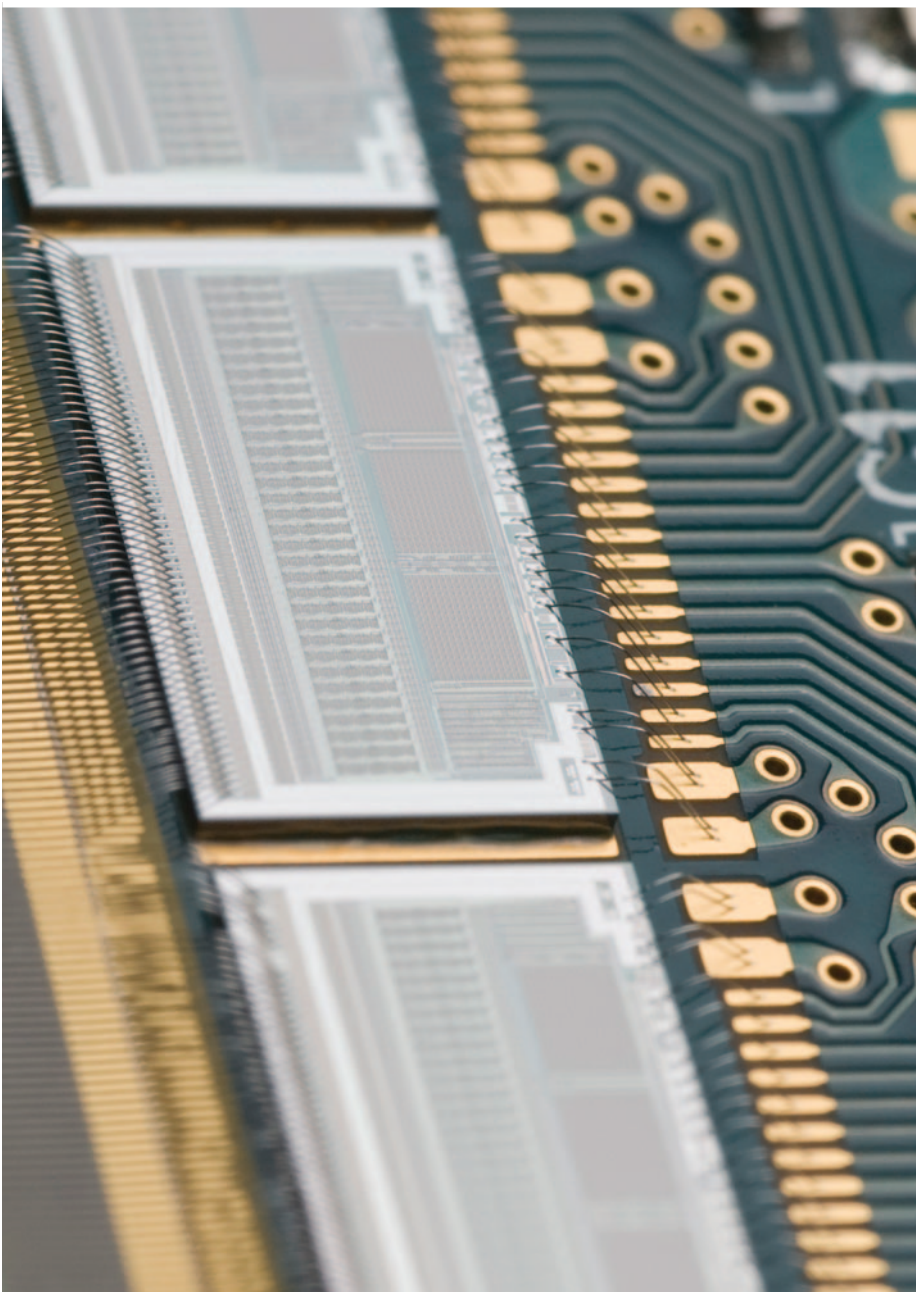
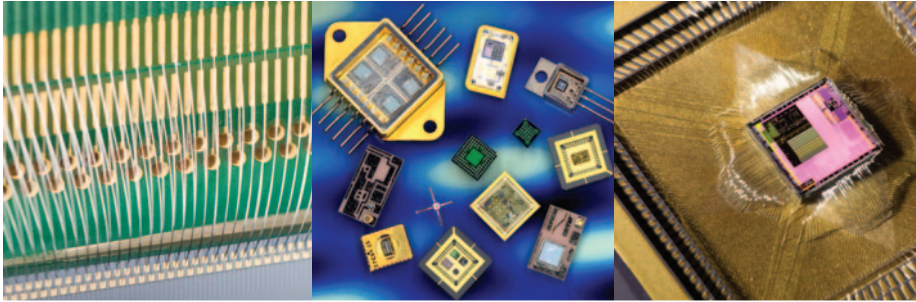


Die based semiconductor solutions for custom packaging of sensors, mems and high reliability microelectronics



MICROSS COMPONENTS LTD SPECIALISES IN DESIGN, ASSEMBLY AND ELECTRICAL TEST OF SEMICONDUCTOR BARE DIE SOLUTIONS FOR A DIVERSE RANGE OF INDUSTRIAL, MEDICAL, AUTOMOTIVE & AEROSPACE APPLICATIONS.





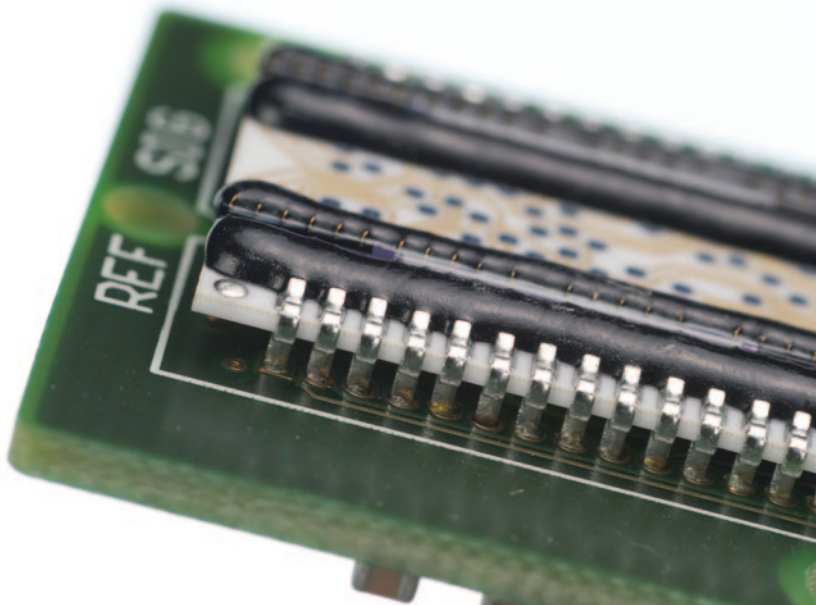
Die based semiconductor solutions for custom packaging of sensors, mems and high reliability microelectronics

SERVICES

- Die & Wafer Processing
- Bare Die Distribution
- Chip On Board
- Hi-Rel Hermetic Packaging
- Die Attach & Wirebond
- Fine Pitch & Staggered Bonding
- Mixed SMT & Die Assembly
- Electrical Burn In & Test
- ASIC Design, Circuit Design
- Miniaturisation using Bare Chip
- Multi-Chip Modules
- Full Custom Packaging Solutions

TECHNOLOGY APPLICATIONS

- Medical Fluidics
- Gas Sensing
- Anaesthetic Delivery
- Automotive Sensors
- Hi-Rel Military Grade
- Space Grade
- Down Hole High Temperature
- MEMS
- RF & Microwave
- LED Arrays
- Photovoltaic Modules



Microcross Components Crewe

11-16 A-Tech Court Lancasterfields
Crewe Cheshire CW1 6FF
Tel: +44 (0)1270 252 566
Fax: +44 (0)1270 252 596

Microcross Components Alton

2 Oriel Court Omega Park
Alton Hampshire GU34 2YT
Tel: +44 (0)1420 594 180
Fax: +44 (0)1420 891 51

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